SCHEDULE AT A GLANCE

| Sun. May 13 | Mon. May 14 | Tue. May 15 | Wed. May 16 | Thu. May 17 |
|---|--|--|--|---|
| Registration Desk 8:00-17:00 Honore Room (Lobby Level) Short Course 1: Silicon Charge Balance Devices 9:00-10:00 Honore Room (Lobby Level) | Registration Desk 7:00-17:00 Red Lacquer Room (4th Level) Plenary 1 8:30-10:20 Red Lacquer Room (4th level) | 3. Lateral Devices: Reliability 8:30-10:10 Red Lacquer Room (4 th level) | 9. GaN Power Devices – 2 8:30-10:10 Red Lacquer Room (4 th level) | 15. Novel Device Structures 8:30-10:10 Red Lacquer Room (4 th level) |
| Coffee Break 10:00-10:15 | Coffee Breek | Coffee Break 10:10-10:30 | Coffee Break 10:10-10:30 | Coffee Break 10:10-10:30 |
| Short Course 2: Device Loss Mechanisms 10:15-11:15 Coffee Break 11:15-11:30 Short Course 3: SiC Device | Coffee Break 10:20-10:40 Salon 4-9 (3rd Level) Plenary 2 10:40-12:10 Red Lacquer Room (4 th level) | Salon 4-9 (3rd Level) 4. Smart Power ICs 10:30-12:10 Red Lacquer Room (4 th level) | Salon 4-9 (3rd Level) Poster Sessions 10. Low Voltage 11. IC Design 12. SiC 10:30-12:10 Salon 4-9 (3rd Level) | Salon 4-9 (3rd Level) 16. IGBTs 10:30-12:10 Red Lacquer Room (4 th level) |
| Design & Fabrication 11:30-12:30 Lunch on Own | Lunch on Own 12:10-14:00 | Lunch on Own 12:10-13:30 | Lunch on Own 12:10-13:30 | Lunch on Own 12:10-13:30 |
| 12:30-14:00 Short Course 4: Vertical GaN Power Devices 14:00-15:00 Coffee Break | 1. Superjunction MOS, Diodes and IGBTs | 5. GaN Power Devices - 1 13:30-15:10 Red Lacquer Room (4 th level) | 13. SiC Reliability and Ruggedness 13:30-15:10 Red Lacquer Room (4 th level) | 17. Invited & Late News Papers 13:30-15:10 Red Lacquer Room (4 th level) |
| 15:00-15:15 Short Course 5: AlGaN/GaN | 14:00-15:40 - Red Lacquer Room (4 th level) | Coffee Break 15:10-15:30 Salon 4-9 (3rd Level) | Coffee Break 15:10-15:30 Salon 4-9 (3rd Level) | Closing 15:10-15:40 Red Lacquer Room (4 th level) |
| Power Device Reliability 15:15-16:15 | Coffee Break 15:40-16:00 | Poster Sessions 6. High Voltage 7. GaN | 44 Dealersing and Enghling | |
| Coffee Break 16:15-16:30 Short Course 6: Power Module Design and Assembly 16:30-17:30 | 2. SiC Power MOSFETs 16:00-18:05 Red Lacquer Room (4 th level) | 8. Packaging 15:30-17:10 Salon 4-9 (3rd Level) | 14. Packaging and Enabling Technologies 15:30-17:35 Red Lacquer Room (4 th level) | |
| | Reception 18:15-20:15 (badge required) Empire Room (Lobby Level) | Ad Com Meeting/Dinner (invitation only) | Banquet 18:30-21:30 (card required) Grand Ballroom (4 th level) | TPC Dinner (invitation only) |